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(12) **United States Design Patent**
Chen

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(54) **HEADPHONE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**

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381/380, 381, 378-379, 374; 455/90.3,
455/575.1, 569.1

CPC H04R 25/00; H04R 25/02; H04R 1/10;
H04R 1/1066; H04R 1/1016; H04R
5/033; H04R 5/0335; H04R 1/1091
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D512,708 S *	12/2005	Harris, Jr.	D14/205
D541,255 S *	4/2007	Taylor	D14/205
D563,382 S *	3/2008	Wikel	D14/205
7,412,070 B2 *	8/2008	Kleinschmidt	H04R 1/1066 381/74
D581,394 S *	11/2008	Lee	D14/205
D585,871 S *	2/2009	Lee	D14/205
D594,847 S *	6/2009	Suzuki	D14/205
D600,674 S *	9/2009	Brennwald	D14/205

D616,865 S *	6/2010	Marchand	D14/205
D642,554 S *	8/2011	Schaal	D14/205
D662,080 S *	6/2012	Carr	D14/205
D691,984 S *	10/2013	Wang	D14/205
D693,791 S *	11/2013	Troy	D14/205
D706,240 S *	6/2014	Szymanski	H04R 1/1066 D14/205
D706,241 S *	6/2014	Szymanski	H04R 1/1066 D14/205
D716,255 S *	10/2014	Cho	D14/205
D719,136 S *	12/2014	Schaal	D14/206
D721,052 S *	1/2015	Carr	D14/205
D734,297 S *	7/2015	Sasaki	D14/205
D741,290 S *	10/2015	Schaal	D14/205
D758,337 S *	6/2016	Szymanski	D14/205
D761,761 S *	7/2016	Ando	D14/205
D780,713 S *	3/2017	Szymanski	D14/205
D800,691 S *	10/2017	Ando	D14/205
D811,364 S *	2/2018	Park	D14/205

(Continued)

FOREIGN PATENT DOCUMENTS

CN	305706780	*	4/2020
CN	306391105	*	3/2021

(Continued)

Primary Examiner — Paula Allen Greene

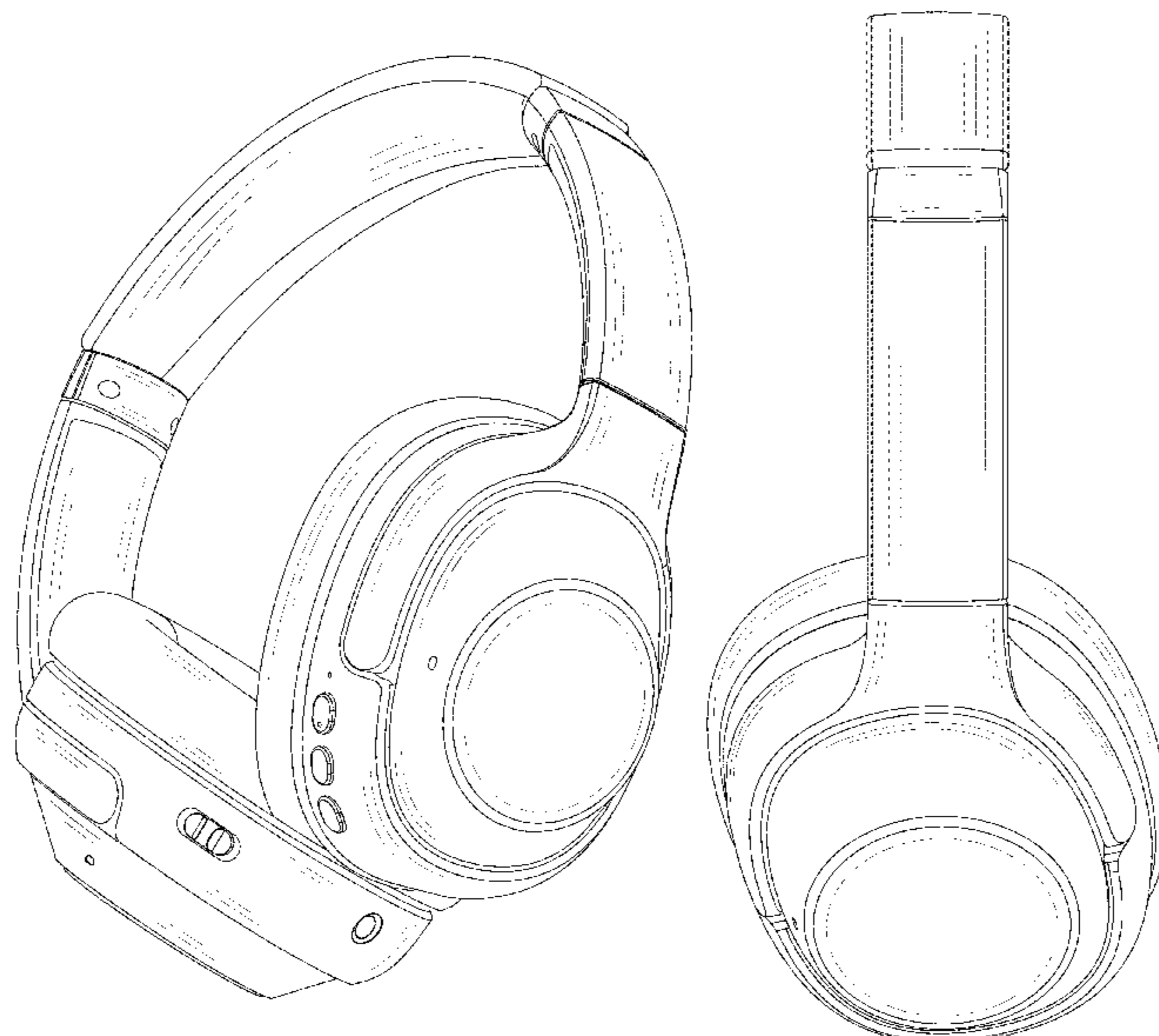
(57) **CLAIM**

The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a headphone showing my new design;
FIG. 2 is a front elevation view thereof;
FIG. 3 is a rear elevation view thereof;
FIG. 4 is a left side elevation view thereof;
FIG. 5 is a right side elevation view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D828,326	S	*	9/2018	Ye	D14/205
D836,084	S	*	12/2018	Xie	D14/205
D837,763	S	*	1/2019	Suzuki	D14/205
D840,370	S	*	2/2019	Kelly	D14/205
D843,345	S	*	3/2019	Brunner	D14/205
D879,065	S	*	3/2020	Chan	D14/205
D908,663	S	*	1/2021	Tamamura	D14/205
D918,171	S	*	5/2021	Nakayama	D14/205
D919,603	S	*	5/2021	Xia	D14/223
D923,600	S	*	6/2021	Shibukawa	D14/205
D936,631	S	*	11/2021	Qin	D14/205
D938,934	S	*	12/2021	Tsubone	D14/205
2004/0216946	A1	*	11/2004	Lenhard-Backhaus	
						H04R 1/1066
						181/129
2010/0310093	A1	*	12/2010	Semcken	H04R 1/1058
						381/104

FOREIGN PATENT DOCUMENTS

CN	306495100	*	4/2021
CN	307054328	*	1/2022
EM	008837025-0001	*	1/2022
EM	008837843-0001	*	1/2022
GB	9006753653-0003	*	8/2019
JP	D1708929	*	2/2022

* cited by examiner

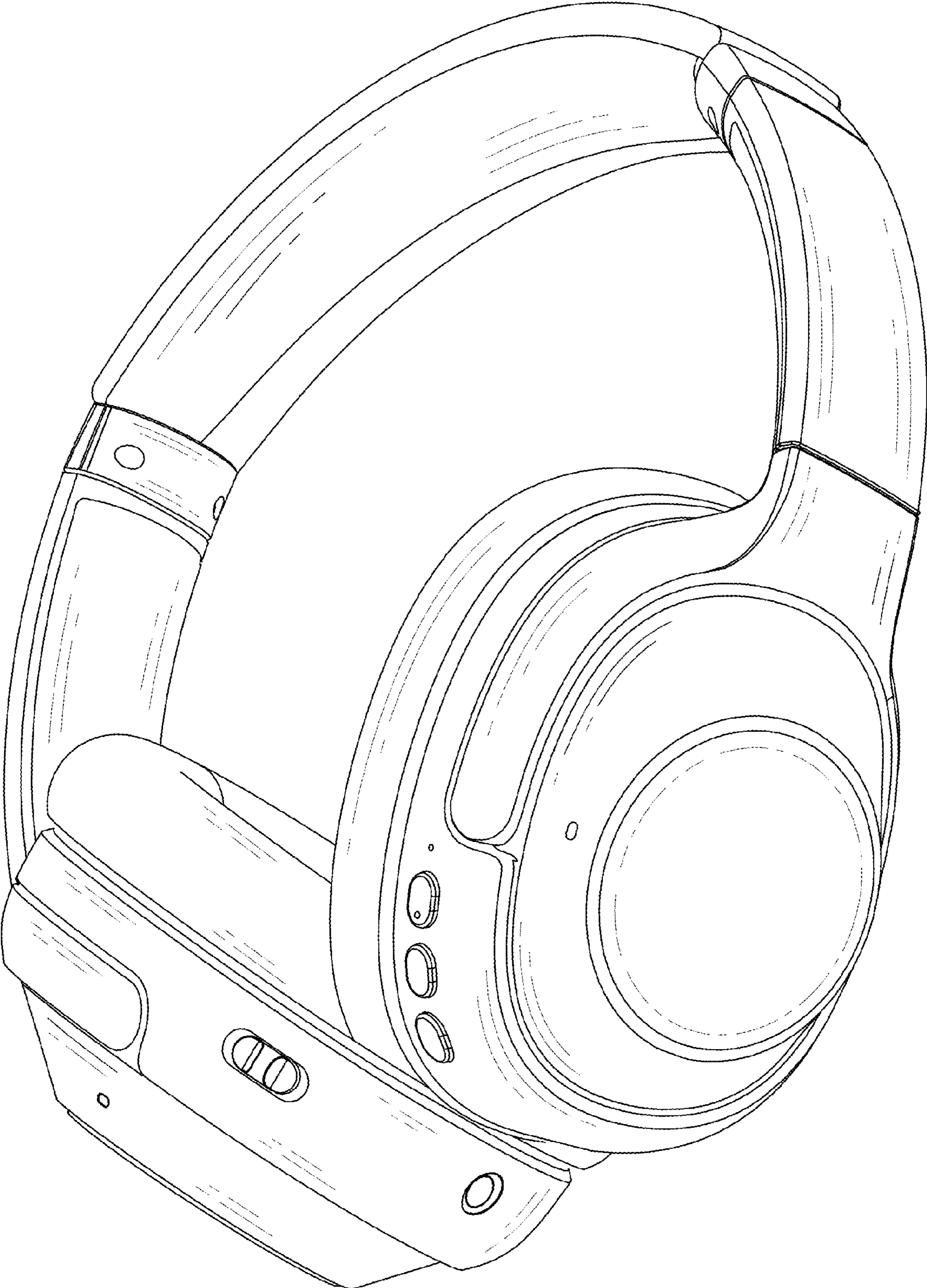


FIG.1



FIG.2

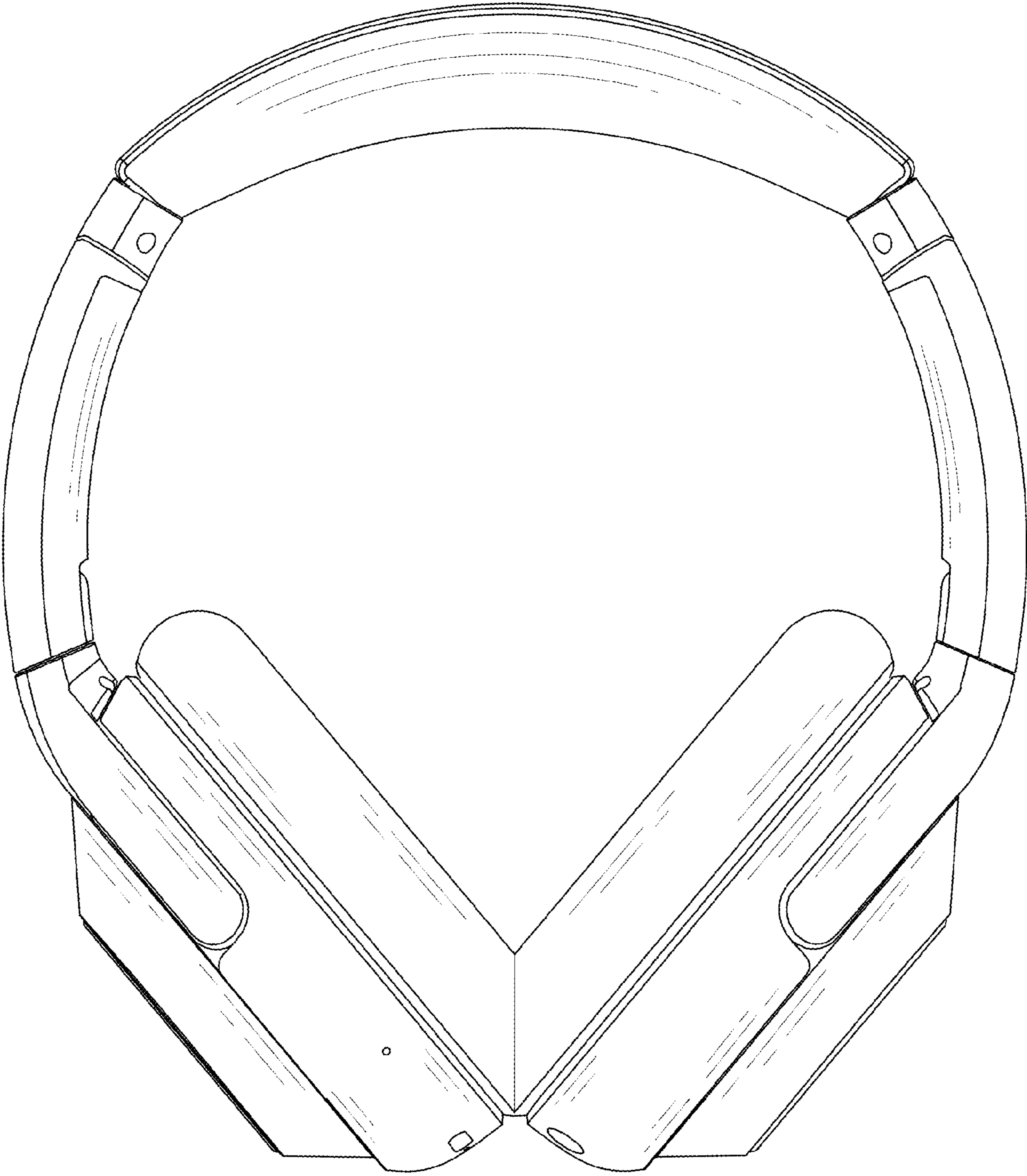


FIG.3

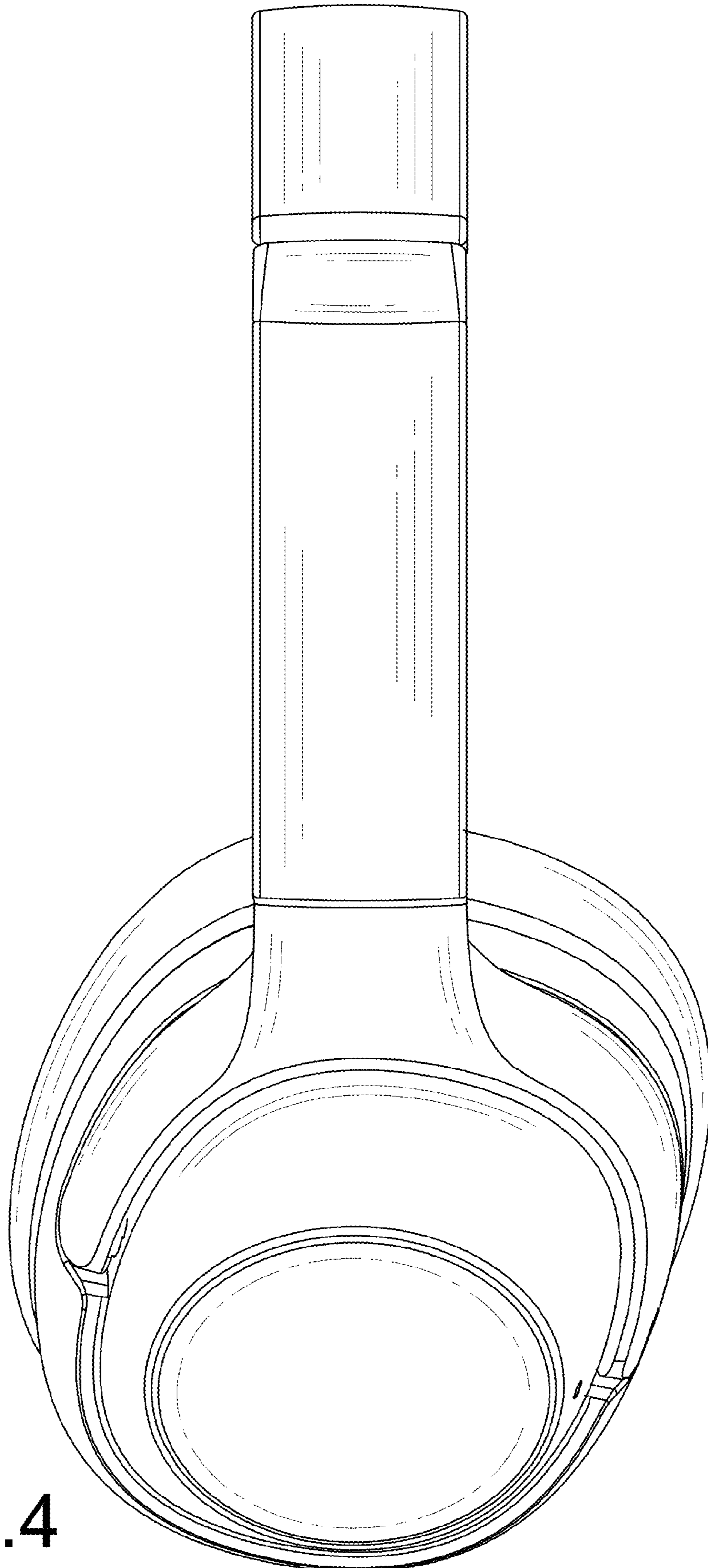


FIG.4

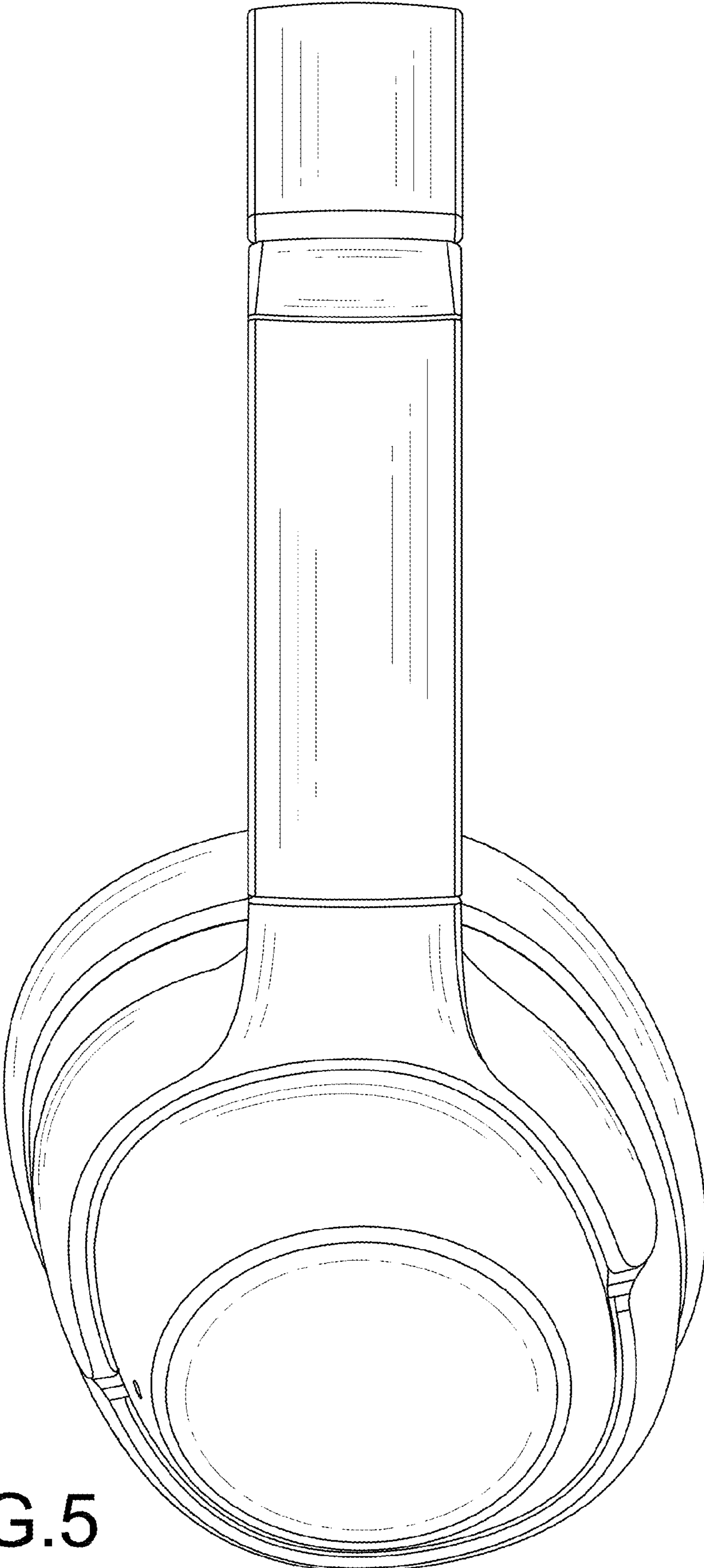


FIG. 5

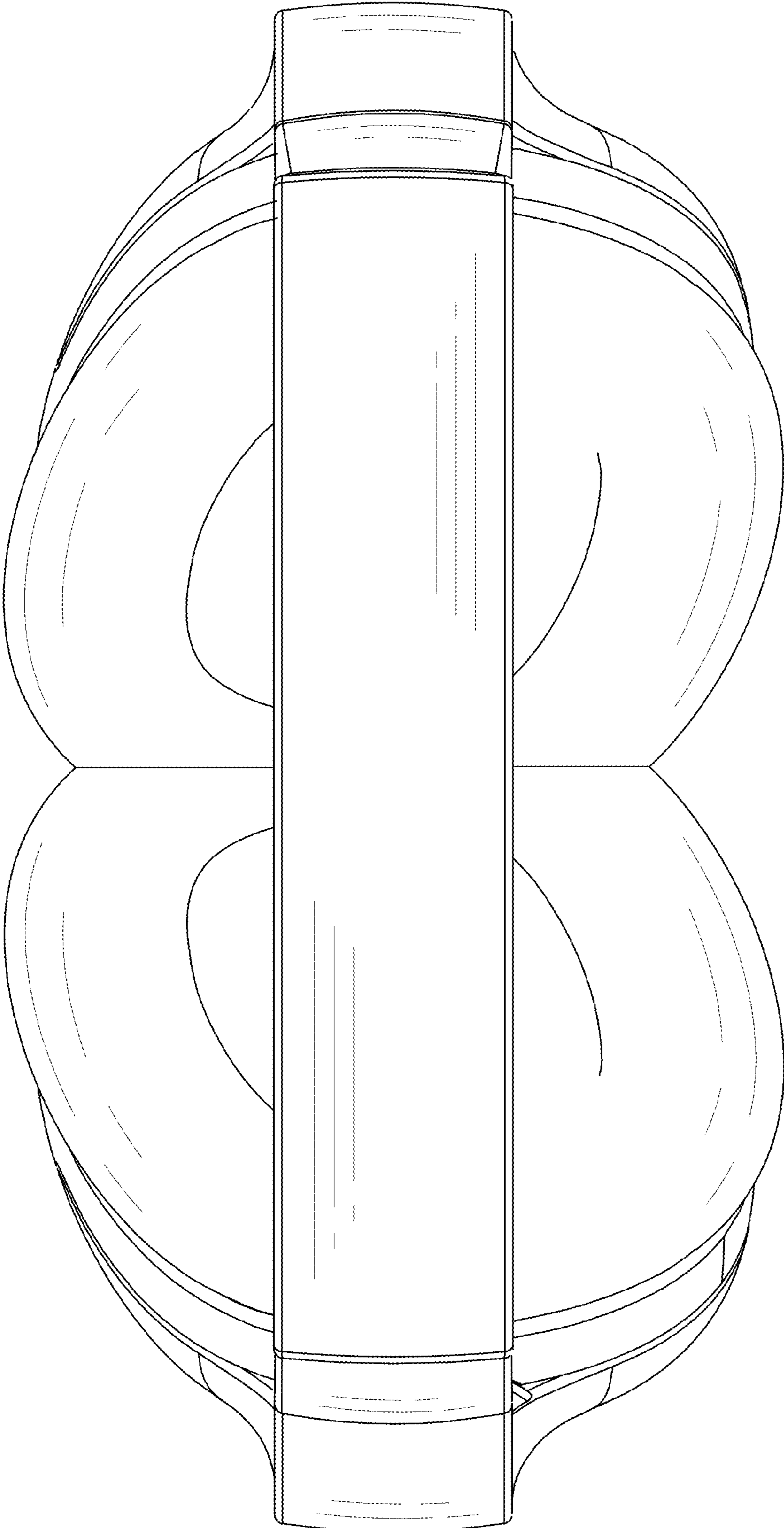


FIG.6

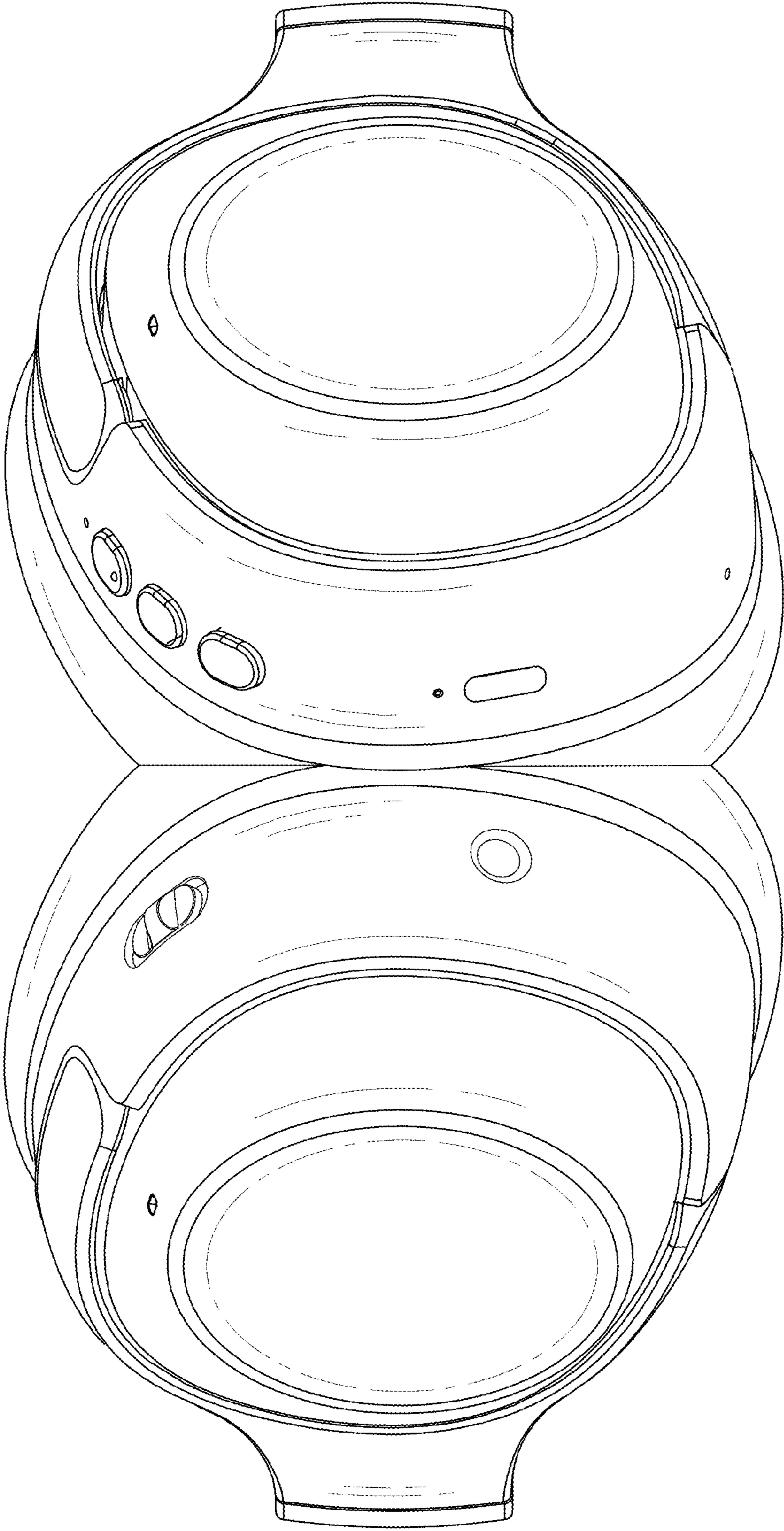


FIG. 7